



Solder plus Support

CASE STUDY

AIM's H10 REL61 Improves Print Quality and Solder Joint Appearance for Automotive LED Assembly

PROBLEM

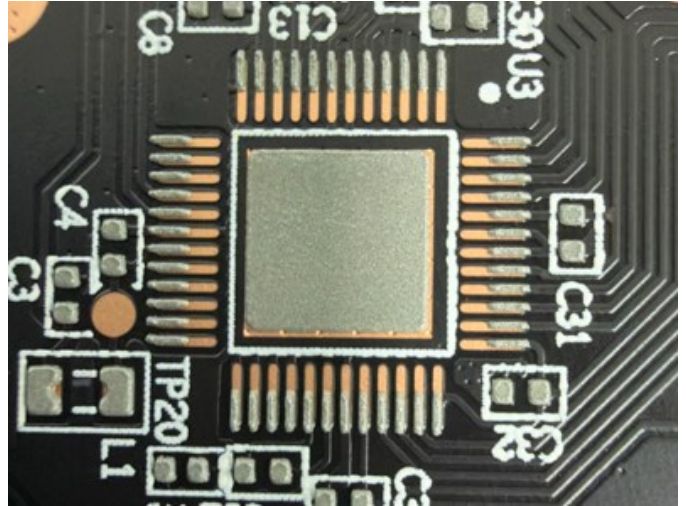
A contract manufacturer was using a competitor's SAC305 solder paste and wanted to assess whether AIM could provide improved overall process performance while supporting potential cost reduction goals. The evaluation focused on print quality, wetting behavior, solder joint appearance, flux residue, and voiding performance.

SOLUTION

AIM supplied H10 REL61, T4 solder paste for evaluation on the customer's existing SMT line. The paste demonstrated strong print performance and deposit shape on 0.50 mm pitch QFPs and chip components. Reflow results showed excellent wetting, uniform solder joint gloss, and minimal flux residue compared to the competitor.

RESULTS

H10 REL61 performed better overall than the incumbent competitor solder paste. The customer was satisfied with the results and planned to continue with reliability testing. Pending acceptable reliability results, the customer intended to place an order and proceed with a small-batch production trial.



PRODUCTS/SERVICES USED

- ▶ [REL61 Cost Saving SAC305 Alternative](#)
- ▶ [H10 Halogen Free No Clean Solder Paste](#)
- ▶ [AIM Solder Technical Support](#)

SUCCESS METRICS

- ▶ Improved paste deposit shape compared to incumbent
- ▶ Uniform solder joint gloss and minimal flux residue
- ▶ Improved wetting performance
- ▶ Cost savings

LEARN MORE

Learn more about the cost saving and performance benefits of REL61 from AIM experts:

- ▶ [AIM's REL61 Solder Alloy](#)
- ▶ [Beat the Silver Cost Surge](#)